

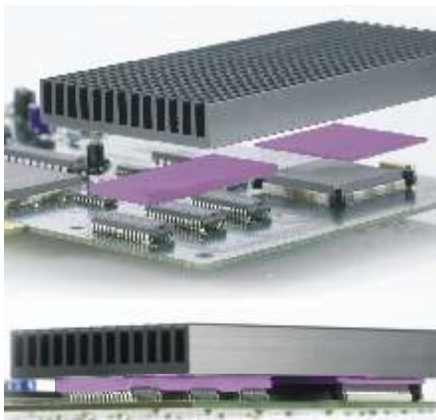
Keratherm[®] - Softtherm[®] 86/525

The Softtherm[®] 86/525 has a very good thermal behaviour. The film is characterized by very good compressibility, low thermal resistance and best heat dissipation.

The film is designed for optimal thermal connections in the fields of computer technology and high-performance automotive applications. With its outstanding thermal conductivity and very good compressibility the film is very well suited for these types of applications. The material's good formability reduces mechanical stress on the power components.

Applications:

- RD-RAM memory modules
- Heat pipe thermal solutions
- Automotive engines
- Control units
- Plasma supply console



*Youngs modulus sample size
30mmx30mmx2.5mm; variable contact pressure;
compression 50% of the measured thickness
***Kerafol test according to UL

Properties	Unit	86/525
Colour		violett
Thermal properties		
Thermal resistance R_{th}	K/W	0.22
Thermal impedance R_{ti}	$^{\circ}Cmm^2/W$	89
	Kin^2/W	0.14
Thermal conductivity λ	W/mK	5.5
Electrical properties		
Breakdown voltage $U_{d; ac}$	kV	1.5
Dielectric breakdown $E_{d; ac}$	kV/mm	2.5
Volume resistivity	Ωm	16×10^{12}
Dielectric loss factor $\tan \delta$	1	1.0×10^{-3}
Dielectric constant ϵ_r	1	2.7
Mechanical properties		
Measured thickness (+/-10%)	mm	0.5
Hardness	Shore 00	50 - 60
Youngs modulus*	N/cm ²	98.5
Physical properties		
Density	g/cm ³	1.18
Application temperature	$^{\circ}C$	-40 to +180
TML	Ma.-%	< 0.35
Flame class	UL	94V-0
Possible thickness**	mm	0.5 - 3.0

